

Abstract of the Disclosure

A pressure transducer includes a carrier having a central aperture for receiving fluid from a vessel. A sense die mounts on the carrier having a first side configured to interact with a fluid from the vessel. A gel attaches the sense die to the carrier. Pressure-sensing circuitry is formed on a second side of the sense die not exposed to the fluid. Further, a ceramic board mounts on the carrier, the ceramic board has conductive paths electrically connecting the pressure-sensing circuitry. Circuitry other than the pressure-sensing circuitry also mounts on the ceramic board and is electrically connected to the conduction paths. A hermetically-sealed cover configured to prevent the fluid or other external elements from contacting the second side of the sense die wherein the cover creates a defined volume surrounding the second side.